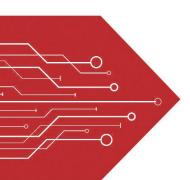
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

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- Extremely Fast Switching Speed
- Low forward voltage











MARKING:

BAT54W	BAT54AW	BAT54CW	BAT54SW
KL5	KL6	KL7	KL8

SOT-323

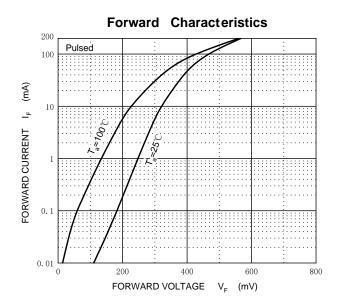
MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

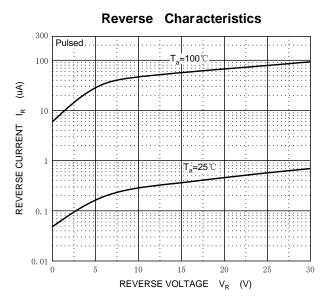
Parameter	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}		
Working Peak Reverse Voltage	V_{RWM}	30	V
DC Blocking Voltage	V_R		
Forward Continuous Current	I _{FM}	200	mA
Non-repetitive Peak Forward Surge Current @t=8.3ms	I _{FSM}	600	mA
Repetitive Peak Forward Current @ $t \le 1s$, $\delta \le 0.5$	I _{FRM}	300	mA
Power Dissipation	P _D	200	mW
Thermal Resistance from Junction to Ambient	$R_{\Theta JA}$	500	°C/W
Operating Junction Temperature Range	Tj	-40 ~ +125	℃
Storage Temperature Range	T _{stg}	-55 ~ +150	℃

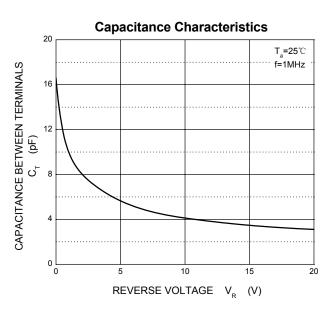
ELECTRICAL CHARACTERISTICS(Ta=25℃ unless otherwise specified)

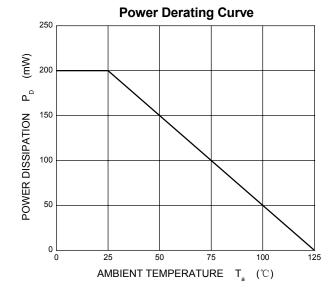
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	V _(BR)	I _R =100μA	30			V
Reverse current	I _R	V _R =25V			2	μA
		I _{F1} =0.1mA			0.24	V
		I _{F2} =1mA			0.32	V
Forward voltage	V _F	I _{F3} =10mA			0.40	V
		I _{F4} =30mA			0.50	V
		I _{F5} =100mA			1	V
Diode capacitance	C _D	V _R =1V, f=1MHz			10	pF
	,	IF=IR=10mA			_	
Reverse recovery time	t _{rr}	Irr=0.1 \times IR,RL=100 Ω		5	ns	





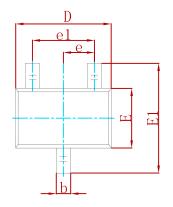


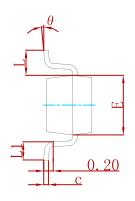


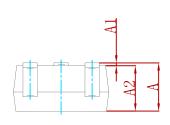




PACKAGE MECHANICAL DATA

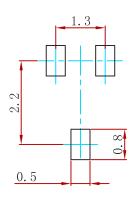






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.200	0.400	0.008	0.016	
С	0.080	0.150	0.003	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.450	0.085	0.096	
е	0.650 TYP		0.026 TYP		
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021	REF	
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAT54AW	SOT-323	3000





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